

# NTR4502P, NVTR4502P

## Power MOSFET

–30 V, –1.95 A, Single, P–Channel,  
SOT–23

### Features

- Leading Planar Technology for Low Gate Charge / Fast Switching
- Low  $R_{DS(on)}$  for Low Conduction Losses
- SOT–23 Surface Mount for Small Footprint (3 X 3 mm)
- AEC Q101 Qualified – NVTR4502P
- These Devices are Pb–Free and are RoHS Compliant

### Applications

- DC to DC Conversion
- Load/Power Switch for Portables and Computing
- Motherboard, Notebooks, Camcorders, Digital Camera's, etc.
- Battery Charging Circuits

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DS}$	–30	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current (Note 1)	$t < 10 \text{ s}$	$T_A = 25^\circ\text{C}$	$I_D$ –1.95 A
		$T_A = 70^\circ\text{C}$	–1.56
Power Dissipation (Note 1)	$t < 10 \text{ s}$	$P_D$	1.25 W
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	$I_D$ –1.13 A
		$T_A = 70^\circ\text{C}$	–0.90
Power Dissipation (Note 1)	Steady State	$P_D$	0.4 W
Pulsed Drain Current	$t_p = 10 \mu\text{s}$	$I_{DM}$	–6.8 A
Operating Junction and Storage Temperature	$T_J, T_{STG}$	–55 to 150	$^\circ\text{C}$
Source Current (Body Diode)	$I_S$	–1.25	A
Lead Temperature for Soldering Purposes (1/8 in from case for 10 s)	$T_L$	260	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 1)	$R_{\theta JA}$	300	$^\circ\text{C/W}$
Junction-to-Ambient – $t = 10 \text{ s}$ (Note 1)	$R_{\theta JA}$	100	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface-mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [1 oz] including traces).

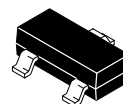
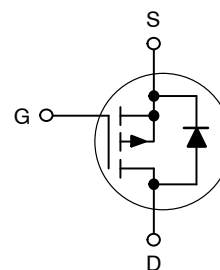


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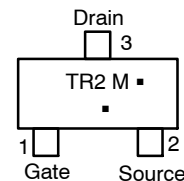
$V_{(BR)DS}$	$R_{DS(on)}$ TYP	$I_D$ Max (Note 1)
–30 V	155 m $\Omega$ @ –10 V	–1.95 A
	240 m $\Omega$ @ –4.5 V	

### P–Channel MOSFET



SOT–23  
CASE 318  
STYLE 21

### MARKING DIAGRAM/ PIN ASSIGNMENT



TR2 = Device Code  
M = Date Code\*  
■ = Pb–Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
NTR4502PT1G	SOT–23 (Pb–Free)	3000 / Tape & Reel
NVTR4502PT1G	SOT–23 (Pb–Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NTR4502P, NVTR4502P

## Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = -30\text{ V}$	$T_J = 25^\circ\text{C}$		-1	$\mu\text{A}$
			$T_J = 55^\circ\text{C}$		-10	
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA

### ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\text{ }\mu\text{A}$	-1.0		-3.0	V
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -1.95\text{ A}$		155	200	$\text{m}\Omega$
		$V_{GS} = -4.5\text{ V}, I_D = -1.5\text{ A}$		240	350	
Forward Transconductance	$g_{FS}$	$V_{DS} = -10\text{ V}, I_D = -1.25\text{ A}$		3		S

### CHARGES AND CAPACITANCES

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = -15\text{ V}$		200		pF
Output Capacitance	$C_{OSS}$			80		
Reverse Transfer Capacitance	$C_{RSS}$			50		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -10\text{ V}, V_{DS} = -15\text{ V}; I_D = -1.95\text{ A}$		6	10	nC
Threshold Gate Charge	$Q_{G(TH)}$			0.3		
Gate-to-Source Charge	$Q_{GS}$			1		
Gate-to-Drain Charge	$Q_{GD}$			1.7		

### SWITCHING CHARACTERISTICS (Note 4)

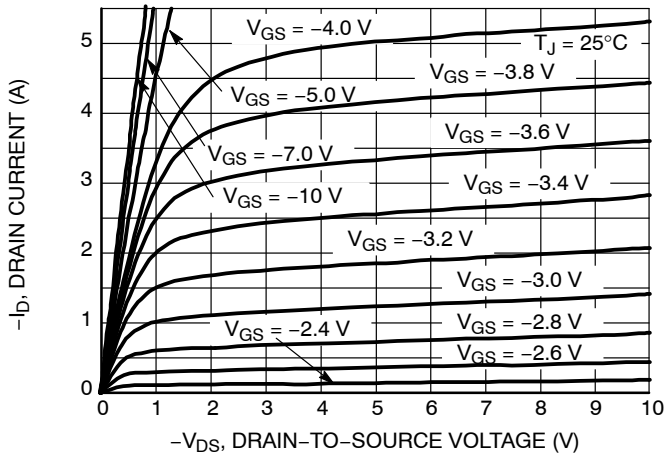
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -10\text{ V}, V_{DD} = -15\text{ V}, I_D = -1.95\text{ A}, R_G = 6\text{ }\Omega$		5.2	10	ns
Rise Time	$t_r$			12	20	
Turn-Off Delay Time	$t_{d(OFF)}$			19	35	
Fall Time	$t_f$			17.5	30	

### DRAIN-SOURCE DIODE CHARACTERISTICS (Note 3)

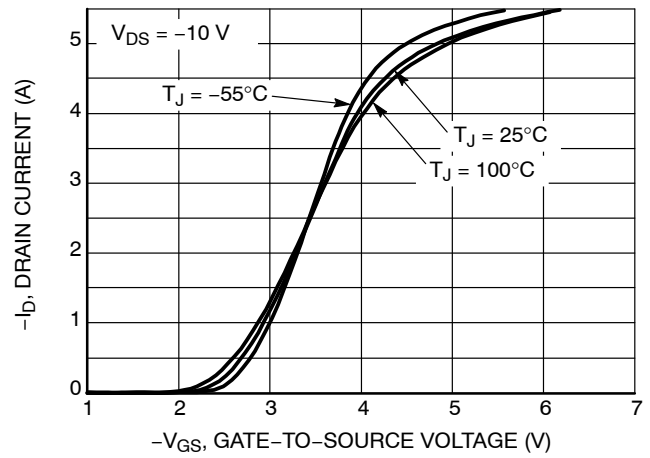
Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = -1.25\text{ A}$		-0.8	-1.2	V
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0\text{ V}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}, I_S = -1.25\text{ A}$		23		ns

- Surface-mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [1 oz] including traces).
- Pulse Test: pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Switching characteristics are independent of operating junction temperatures.

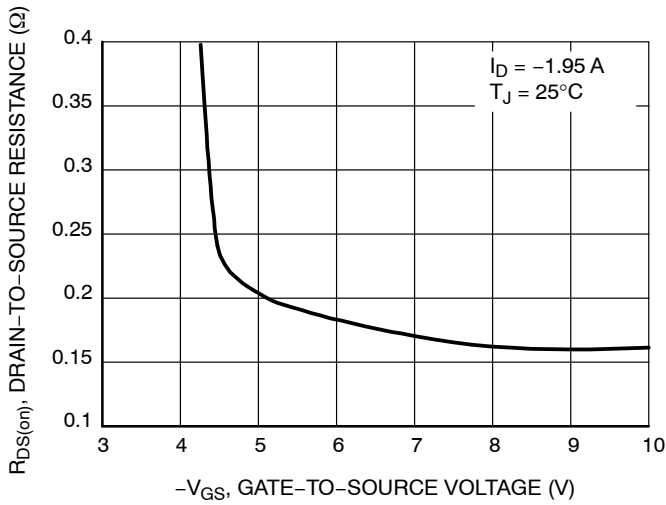
# NTR4502P, NVTR4502P



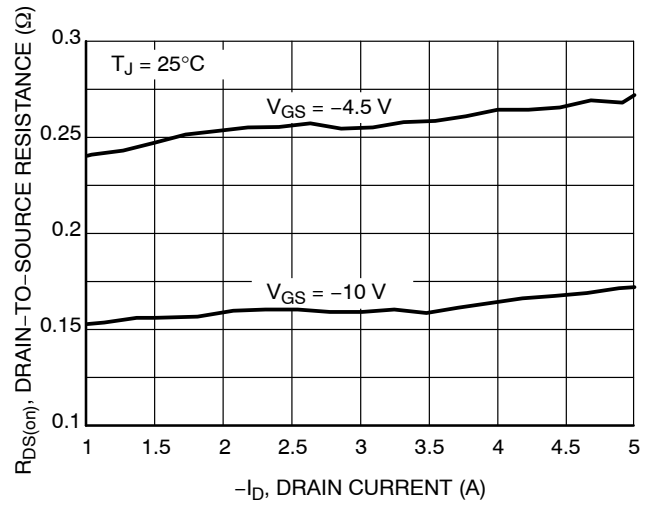
**Figure 1. On-Region Characteristics**



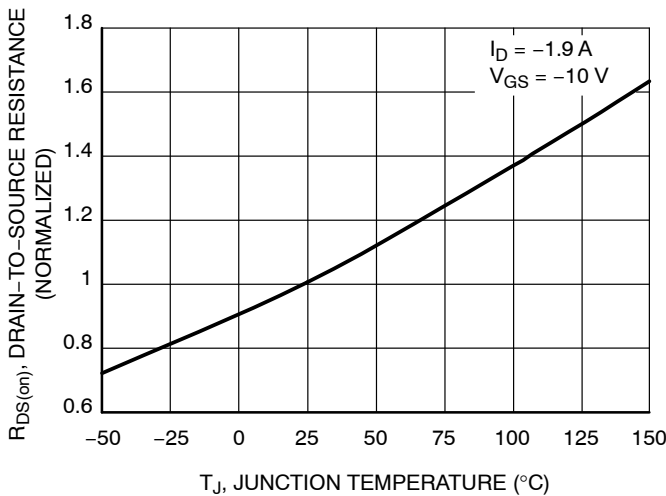
**Figure 2. Transfer Characteristics**



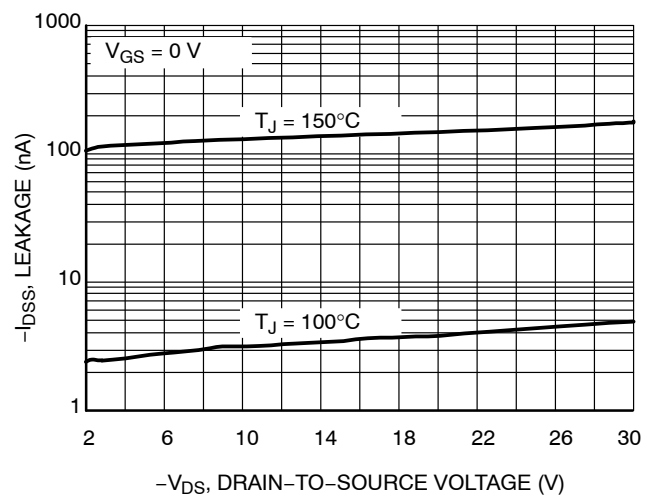
**Figure 3. On-Resistance versus Gate-to-Source Voltage**



**Figure 4. On-Resistance versus Drain Current and Gate Voltage**



**Figure 5. On-Resistance Variation with Temperature**



**Figure 6. Drain-to-Source Leakage Current versus Voltage**

# NTR4502P, NVTR4502P

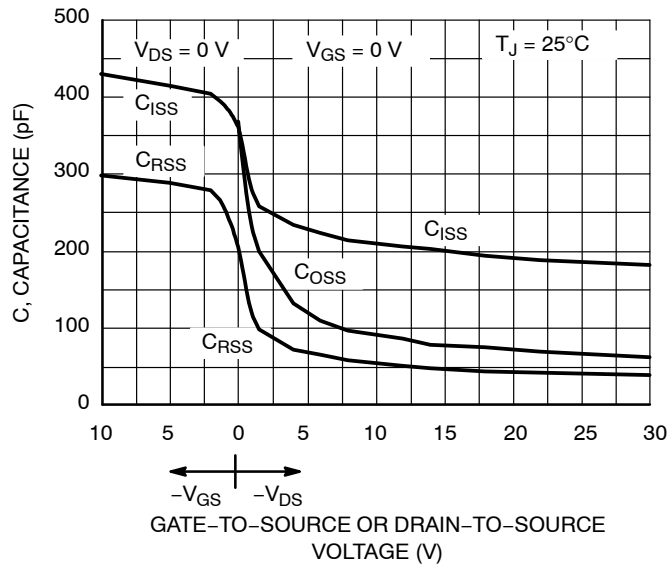


Figure 7. Capacitance Variation

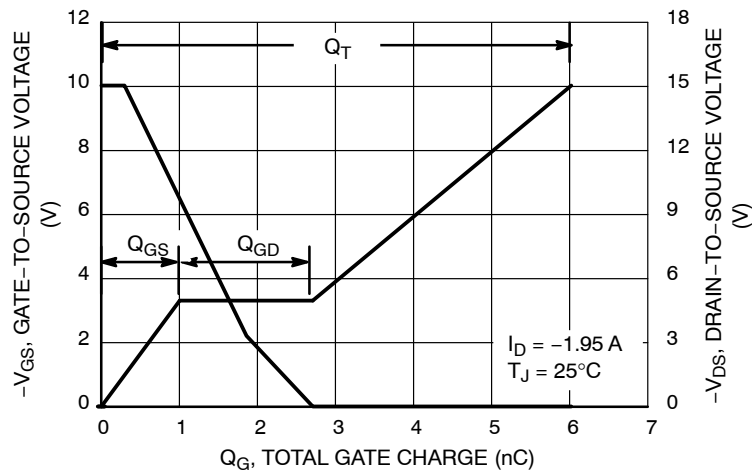


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

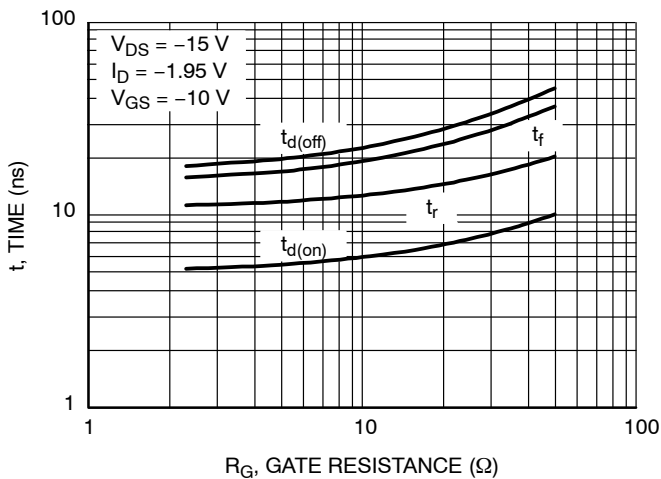


Figure 9. Resistive Switching Time Variation versus Gate Resistance

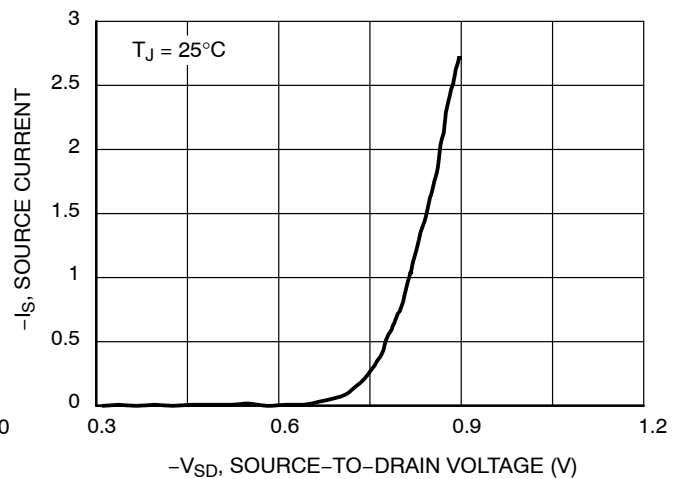
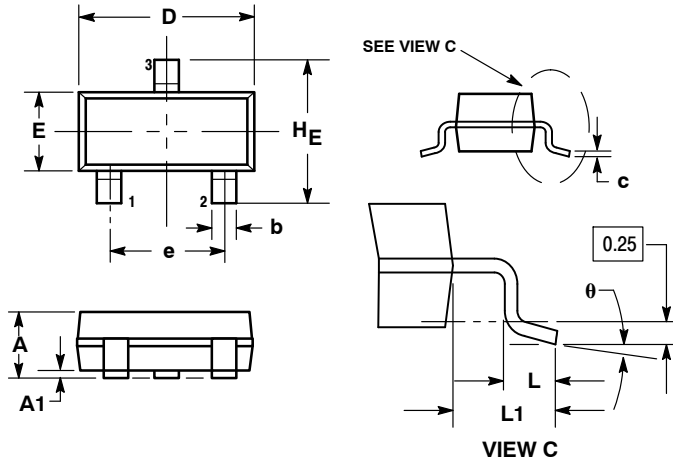


Figure 10. Diode Forward Voltage versus Current

# NTR4502P, NVTR4502P

## PACKAGE DIMENSIONS

### SOT-23 (TO-236) CASE 318-08 ISSUE AP

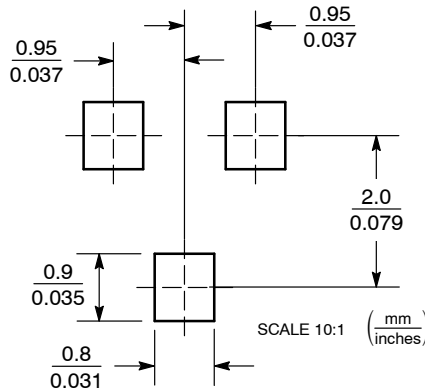


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 21:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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